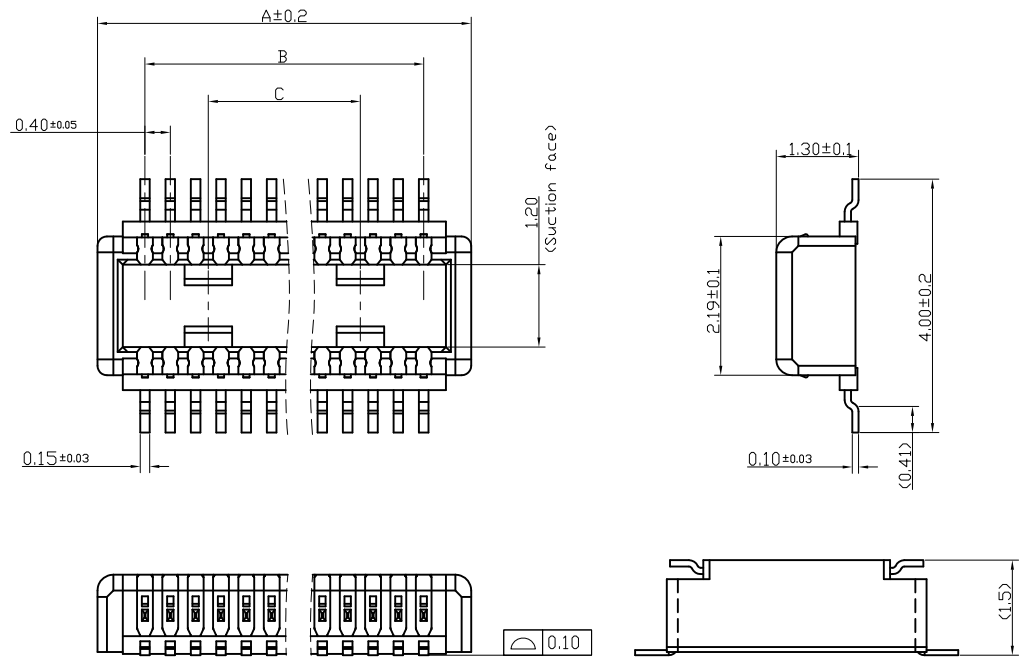


| REV | ECN NO | DRA | APPD | DATE |
|-----|---------------|------------|------------|------------|
| A | FIRST RELEASE | George Gao | Human Zhou | 2013.09.18 |
| | | | | |
| | | | | |



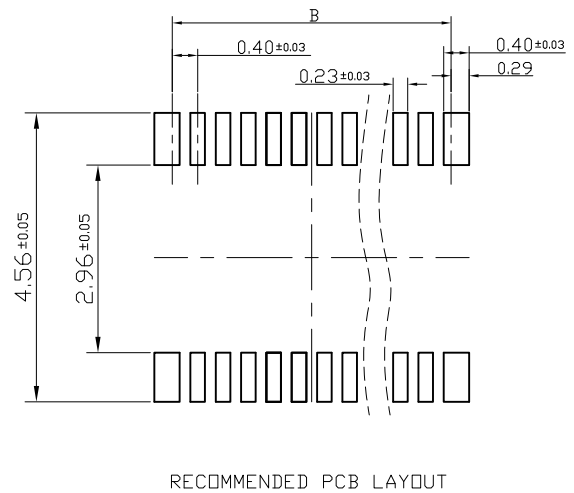
Specifications:

- Material:
 - Molded portion: LCP resin (UL94 V-0)
 - Contact and Post: Copper alloy.
- Surface treatment:
 - Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) ; Exposed nickel portions.
 - Metal clips: Base: Ni plating Surface: Au flash plating (except the terminal tips) Or Base: Ni plating Surface: Sn flash plating (except the terminal tips)
- Characteristics:
 - Rated voltage: 60V AC/DC
 - Rated current: 0.3A/contact (Max. 5A at total contact)
 - Insulation resistance: Min. 1000MΩ (initial)
 - Breakdown voltage: 150V AC for 1 min.
 - Saltwater spray resistance (header and socket mated): 24 hours, insulation resistance min.100MΩ, contact resistance max. 90mΩ
 - Contact resistance: Max. 90mΩ
 - Ambient temperature: -55°C~+85°C
 - Storage temperature: -55°C~+85°C (product only); -40°C~+50°C (emboss packing)
 - Composite insertion force: Max. 0.981N/contacts X contacts (initial)
 - Composite removal force: Min. 0.165N/contacts X contacts
 - Post holding force: Min. 0.49N/contacts
 - Insertion and removal life: 30 times

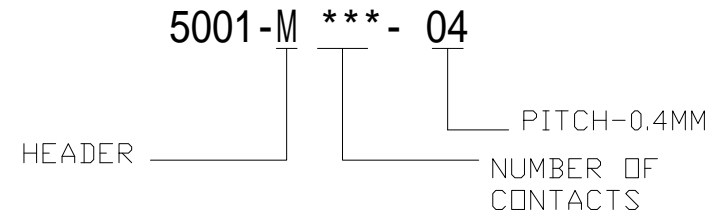
MATING SECTION

TABLE:

| | | | |
|--------------------|-------|-------|-------|
| 70 | 15.10 | 13.60 | 11.60 |
| 60 | 13.10 | 11.60 | 9.60 |
| 50 | 11.10 | 9.60 | 7.60 |
| 40 | 9.10 | 7.60 | 5.60 |
| 30 | 7.10 | 5.60 | 3.60 |
| 24 | 5.90 | 4.40 | 2.40 |
| 20 | 5.10 | 3.60 | 1.60 |
| NUMBER OF CONTACTS | A | B | C |



RECOMMENDED PCB LAYOUT



| DIMENTION IN mm | |  深圳市文章济美科技有限公司 Shenzhen WenZhangJiMei technology co., LTD | | | |
|--------------------------------------|-----------|--|---------------------------------------|------|------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | APPD: | TITLE: 0.4MM BTB (MATING HEIGHT 1.5H) | | |
| . ±0.20 | . ±2* | CHKD: | DWG NO: 5001-M***-04 | | |
| .0 ±0.10 | .0 ±1* | DRA: George Gao 2013.09.18 | | | |
| .00 ±0.03 | .00±0.3* | PROJ | Q'TY | SIZE | SHEETSCALE |
| .000±0.01 | .000±0.1* | --- | --- | A4 | 1/1 1:1 |
| | | REV | A | | |

| REV | ECN NO | DRA | APPD | DATE |
|-----|---------------|------------|------------|------------|
| A | FIRST RELEASE | George Gao | Human Zhou | 2013.09.12 |
| | | | | |
| | | | | |

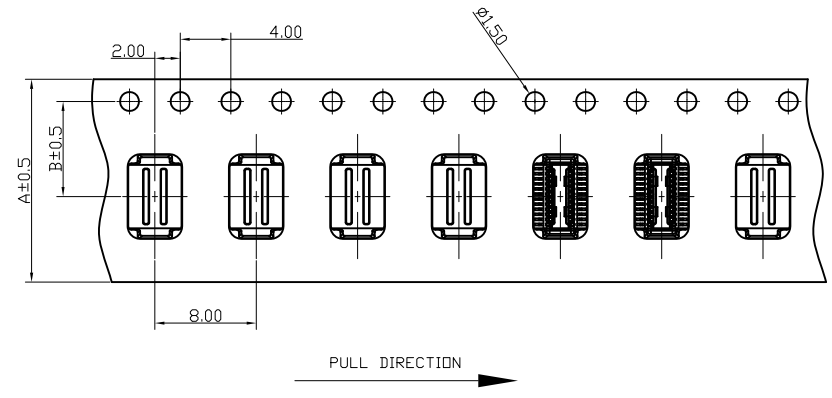
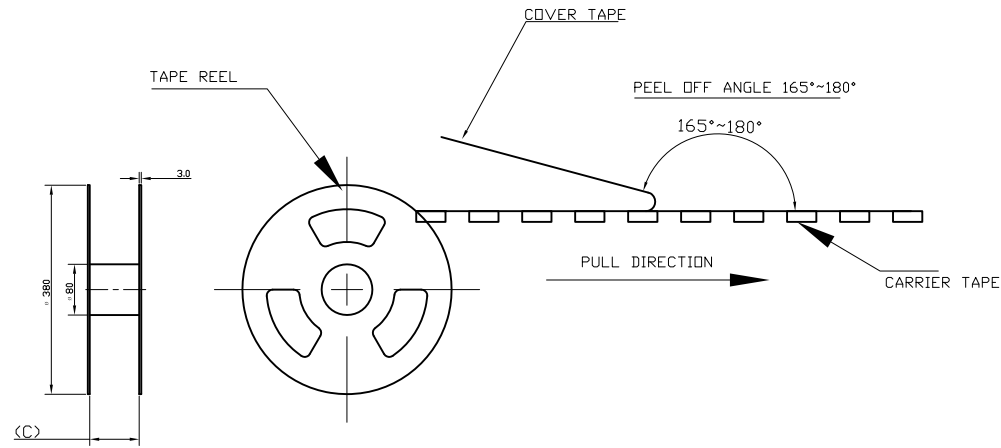
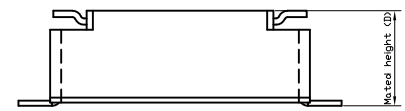
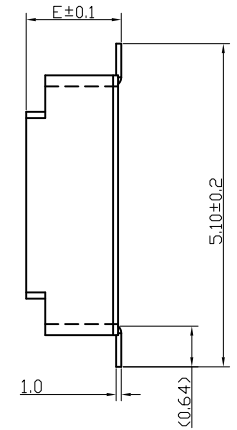
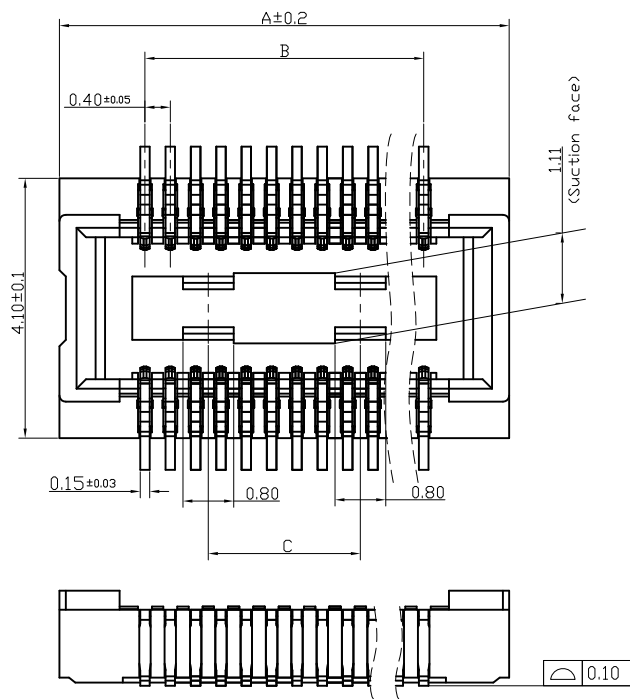


TABLE:

| | | | | |
|--------------------|-------|-------|------|----------|
| 70 | 24.00 | 11.50 | 25.4 | 8000 |
| 60 | | | | |
| 50 | | | | |
| 40 | | | | |
| 30 | 16.00 | 7.50 | 17.4 | |
| 24 | | | | |
| 20 | | | | |
| NUMBER OF CONTACTS | A | B | C | QTY/REEL |

| | | | |
|--------------------------------------|-----------|--|--------------------------------|
| DIMENTION IN mm | |  深圳市文章济美科技有限公司 Shenzhen WenZhangJiMei technology co., LTD | |
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | APPD: | TITLE: |
| . ±0.20 | . ±2' | CHKD: | 0.4MM BTB (MATING HEIGHT 1.5H) |
| .0 ±0.10 | .0 ±1' | | DWG NO: |
| .00 ±0.03 | .00±0.3' | DRA: | PROJ |
| .000±0.01 | .000±0.1' | George Gao 2013.09.18 | Q'TY |
| | | SIZE | SHEET |
| | | A4 | 1/1 |
| | | SCALE | 1:1 |
| | | REV | A |

| REV | ECN NO | DRA | APPD | DATE |
|-----|---------------|------------|------------|------------|
| A | FIRST RELEASE | George Gao | Human Zhou | 2013.09.18 |
| | | | | |
| | | | | |



MATING SECTION

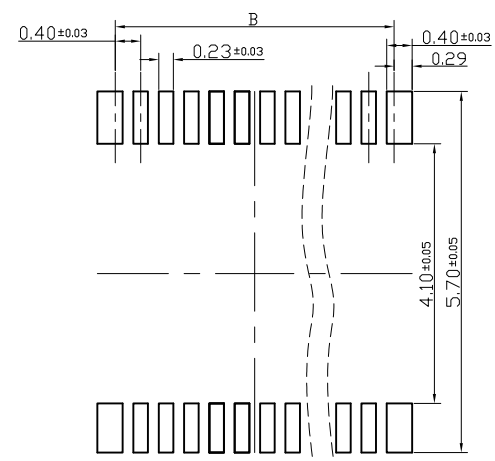
Specifications:

- 1) Material:
 - 1-1. Molded portion: LCP resin (UL94 V-0)
 - 1-2. Contact and Post: Copper alloy.
- 2) Surface treatment:
 - 2-1. Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) ; Exposed nickel portions.
 - 2-2. Metal clips: Base: Ni plating Surface: Au flash plating (except the terminal tips) Or Base: Ni plating Surface: Sn flash plating (except the terminal tips)
- 3) Characteristics:
 - 3-1. Rated voltage: 60V AC/DC
 - 3-2. Rated current: 0.3A/contact (Max. 5A at total contact)
 - 3-3. Insulation resistance: Min. 1000MΩ (initial)
 - 3-4. Breakdown voltage: 150V AC for 1 min.
 - 3-5. Saltwater spray resistance (header and socket mated): 24 hours, insulation resistance min.100MΩ, contact resistance max. 90mΩ
 - 3-6. Contact resistance: Max. 90mΩ
 - 3-7. Ambient temperature: -55°C~+85°C
 - 3-8. Storage temperature: -55°C~+85°C (product only); -40°C~+50°C (emboss packing)
 - 3-9. Composite insertion force: Max. 0.981N/contacts X contacts (initial)
 - 3-10. Composite removal force: Min. 0.165N/contacts X contacts
 - 3-11. Post holding force: Min. 0.49N/contacts
 - 3-12. Insertion and removal life: 30 times

TABLE:

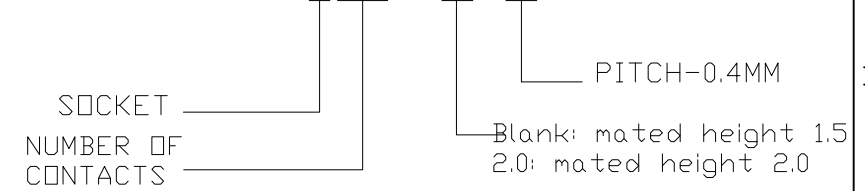
| NUMBER OF CONTACTS | A | B | C | E |
|--------------------|-------|-------|-------|-------------|
| 24 | 7.10 | 4.40 | 2.40 | 1.50 / 1.92 |
| 30 | 8.30 | 5.60 | 3.60 | 1.50 / 1.92 |
| 40 | 10.30 | 7.60 | 5.60 | 1.50 |
| 50 | 12.30 | 9.60 | 7.60 | 1.50 |
| 54 | 13.10 | 10.40 | 8.40 | 1.50 |
| 60 | 14.30 | 11.60 | 9.60 | 1.50 |
| 70 | 16.30 | 13.60 | 11.60 | 1.50 |

| Mated height (D) | E |
|------------------|------|
| 1.5mm | 1.50 |
| 2.0mm | 1.92 |



RECOMMENDED PCB LAYOUT

5001-F***-(**)04



| DIMENTION IN mm | |  深圳市文章济美科技有限公司 Shenzhen WenZhangJiMei technology co., LTD | | | |
|--------------------------------------|-----------|---|---|------|------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | APPD: | TITLE: 0.4MM BTB (MATING HEIGHT 1.5H 2.0H) | | |
| . ±0.20 | . ±2* | CHKD: | DWG NO: 5001-F***-04 | | |
| .0 ±0.10 | .0 ±1* | DRA: George Gao 2013.09.18 | | | |
| .00 ±0.03 | .00±0.3* | PROJ | Q'TY | SIZE | SHEETSCALE |
| .000±0.01 | .000±0.1* | George Gao | -- | A4 | 1/1 1:1 |
| | | REV | A | | |

| REV | ECN NO | DRA | APPD | DATE |
|-----|---------------|------------|------------|------------|
| A | FIRST RELEASE | George Gao | Human Zhou | 2013.09.12 |
| | | | | |
| | | | | |

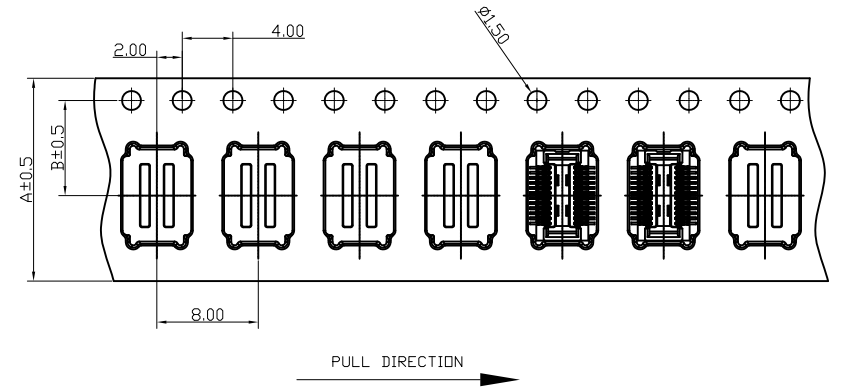
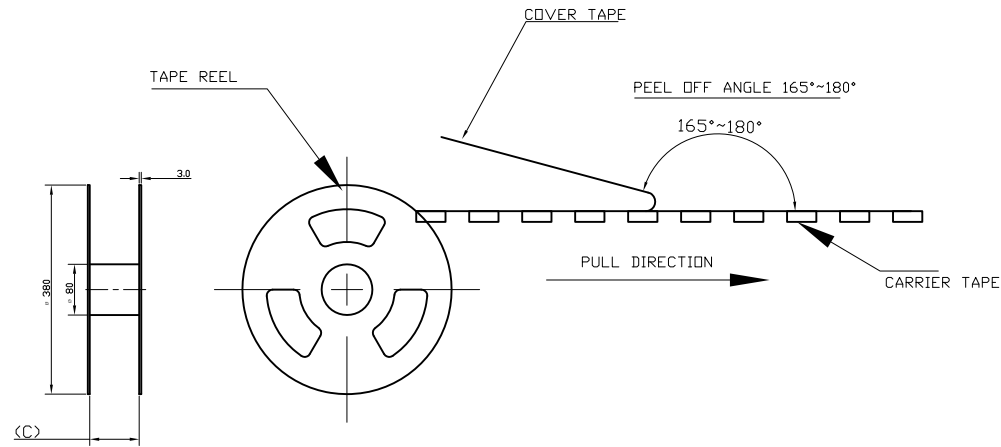


TABLE:

| | | | | |
|----|-------|-------|------|----------|
| 70 | 24.00 | 11.50 | 25.4 | 5000 |
| 60 | | | | |
| 54 | | | | |
| 50 | | | | |
| 40 | 16.00 | 7.50 | 17.4 | |
| 30 | | | | |
| 24 | A | B | C | QTY/REEL |

| DIMENTION IN mm | |  深圳市文章济美科技有限公司 Shenzhen WenZhangJiMei technology co., LTD | | | |
|--------------------------------------|-----------|--|---|------|------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | APPD: | TITLE: 0.4MM BTB (MATING HEIGHT 1.5H 2.0H) | | |
| . ±0.20 | . ±2° | CHKD: | DWG NO: 5001-F***-04 | | |
| .0 ±0.10 | .0 ±1° | DRA: George Gao 2013.09.18 | PROJ | Q'TY | SIZE |
| .00 ±0.03 | .00±0.3° |  | -- | A4 | SHEETSCALE |
| .000±0.01 | .000±0.1° |  | 1/1 | 1:1 | REV A |